

- DO NOT PLACE ANY MARKINGS OR COPPER THEIVING ON TOP OR BOTTOM SIDE OF BOARD UNDER ANTENNA





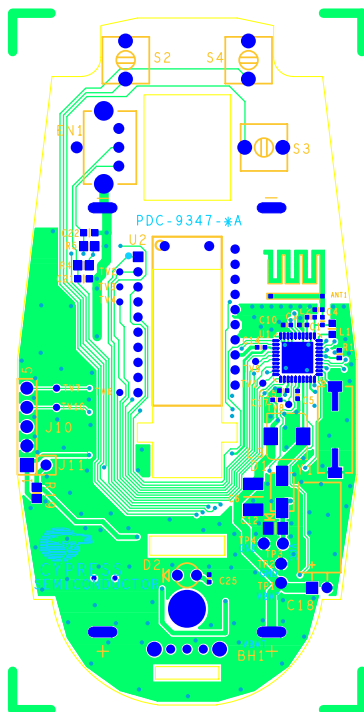
DRILL CHART				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	12.0	± 0.003	PLATED	164
•	15.0	0.003	PLATED	1
•	20.0	0.003	PLATED	9
•	31.0	0.003	PLATED	22
◐	33.0	0.003	PLATED	4
•	35.0	0.003	PLATED	5
•	40.0	0.003	PLATED	9
•	43.0	0.003	PLATED	4
◊	50.0	0.003	PLATED	8
◑	82.0	0.003	PLATED	2
⊙	100.0	0.003	PLATED	1
•	35.0	0.003	NON-PLATED	2
•	55.0	0.003	NON-PLATED	2
•	64.0	0.003	NON-PLATED	1
◐	210.0	0.003	NON-PLATED	1

	OBLONG .033 X .130
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NOTES: (UNLESS OTHERWISE SPECIFIED)

1. MATERIAL:
 - A. EPOXY GLASS LAMINATE AND PREPREG, TYPE FR-4.
 - B. USE HTE COPPER, 1/2 oz. COPPER FOIL EXTERNAL LAYERS AND 1 oz. COPPER FOIL FOR INTERNAL LAYERS, UNLESS OTHERWISE SPECIFIED IN STACKUP VIEW.
 - C. OVERALL METAL TO METAL THICKNESS .063 +/- 10%.
2. DRILLING:
 - A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/- .003 to 1, UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
 - B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
3. PLATING:
 - A. COPPER PLATING IN THRU-HOLES .001 min.
4. MARKING:
 - A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
 - B. FABRICATOR TO ETCH DATE CODE AND LOGO ON SECONDARY SIDE.
5. FINAL FABRICATION:
 - A. SOLDERMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER, PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR **GREEN**
6. WHEN REQUIRED, COPPER FINISH SHALL BE FINISHED TIN-LEAD (60-40 MIN) HASL.
7. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN COPPER ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT.
8. RELIABILITY TESTING (94) AND BURN IN TESTING (WWV).
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .010 in/in.

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	 CYPRESS SEMICONDUCTOR	10147 W. Emerald St. Suite 100 Boise, Idaho 83704 (208) 377-9222	
DIMENSIONS ARE IN INCHES TOLERANCES ON: ANGLES +/- .2°	DRAWN: LARGO	09/01/06			
2 PL DECIMALS +/- .010	CHECKED: LRK	09/01/06			
3 PL DECIMALS +/- .005	ENG'G: LRK	09/01/06			
PROJECTION 	ISSUED		FABRICATION DRAWING PRoC LP MOUSE		
CYPRESS PROPRIETARY THIS DOCUMENT CONTAINS CONFIDENTIAL INFORMATION THAT IS CYPRESS SEMICONDUCTOR PROPERTY. DO NOT DISCLOSE TO OR DUPLICATE FOR OTHERS EXCEPT AS AUTHORIZED BY CYPRESS.			SIZE	FSCM NO	DWG NO
					PDC-9347
			SCALE		SHEET 1 OF 1



PDC-9347-*A PRIMARY SIDE

PDC-9347-*A PRIMARY SILKSCREEN

PDC-0347-A SECONDARY SILKSCREEN
PDC-0347-A SECONDARY SIDE

